

### IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) An integrated circuit comprising:  
a base that includes power contacts which extend from an upper surface of the base to engage a daughterboard that includes to receive power from a voltage source;  
a substrate mounted to the upper surface of the base, the substrate being electrically coupled to the base, wherein the upper surface of the base includes a recess, the substrate being mounted within the recess; and  
a die mounted on the substrate, the die being electrically coupled to the substrate to receive power from the voltage source through the power contacts on the base.
2. (Original) The integrated circuit of claim 1, wherein the voltage source is a voltage regulator.
3. (Canceled)
4. (Original) The integrated circuit of claim 1, wherein the base further includes I/O contacts extending from a bottom surface of the base.
5. (Original) The integrated circuit of claim 4, wherein the power contacts are blade type and the I/O contacts are formed in a large grid array.
6. (Original) The integrated circuit of claim 1, wherein the substrate is surface mounted to the base.
7. (Original) The integrated circuit of claim 1, further comprising a heat spreader coupled to the die.

8. (Original) An electronic assembly comprising:
  - a base that includes power contacts which extend from an upper surface of the base;
  - a substrate mounted to the upper surface of the base;
  - a die mounted on the substrate;
  - a motherboard positioned adjacent to a bottom surface of the base, the motherboard being electrically coupled to the base; and
  - a daughterboard engaging the power contacts on the upper surface of the base to electrically couple a voltage source on the daughterboard to the die.
9. (Original) The electronic assembly of claim 8, wherein the substrate is surface mounted to the base.
10. (Original) The electronic assembly of claim 8, further comprising at least one fastener that compresses the base against the motherboard and the daughterboard.
11. (Original) The electronic assembly of claim 8, further comprising a heat spreader coupled to the die and a heat sink coupled to the heat spreader.
12. (Original) The electronic assembly of claim 11, further comprising at least one fastener to secure the electronic assembly to a chassis.
13. (Original) The electronic assembly of claim 12, wherein the motherboard, the base and the daughterboard are positioned between the heat sink and the chassis when the electronic assembly is coupled to the chassis.
14. (Original) The electronic assembly of claim 8, wherein the upper surface of the base includes a recess, the substrate being mounted within the recess.

15. (Original) The electronic assembly of claim 8, wherein the base further includes I/O contacts extending from a bottom surface of the base to engage the motherboard.

16. (Original) The electronic assembly of claim 15, wherein the power contacts are blade type and the I/O contacts are formed in a large grid array.

17. (Original) An electronic system comprising:  
a bus;  
a memory coupled to the bus;  
an electronic assembly that includes a motherboard and a daughterboard where at least one of the motherboard and the daughterboard are coupled to the bus, the electronic assembly further including a base mounted on the motherboard, a substrate mounted to an upper surface of the base and a die mounted on the substrate, the base including power contacts that extend from the upper surface of the base to engage the daughterboard; and  
a voltage source mounted on the daughterboard to provide power to the die through the power contacts.

18. (Original) The electronic system of claim 17, wherein the base further includes I/O contacts extending from a bottom surface of the base to engage the motherboard.

19. (Original) The electronic system of claim 18, wherein the power contacts are blade type and the I/O contacts are formed in a large grid array.

20. (Original) The electronic system of claim 17, wherein the upper surface of the base includes a recess, the substrate being mounted within the recess.

21. (Original) The electronic system of claim 17, wherein the substrate is surface mounted to the base.

22-28. (Canceled)

29. (New) An integrated circuit comprising:

a base that includes power contacts which extend from an upper surface of the base to receive power from a voltage source, the base further including I/O contacts that extend from a bottom surface of the base, the power contacts being of a blade type and the I/O contacts being formed in a large grid array;

a substrate mounted to the upper surface of the base, the substrate being electrically coupled to the base; and

a die mounted on the substrate, the die being electrically coupled to the substrate to receive power from the voltage source through the power contacts on the base.

30. (New) The integrated circuit of claim 29, wherein the voltage source is a voltage regulator.

31. (New) The integrated circuit of claim 29, further comprising a heat spreader coupled to the die.

32. (New) An integrated circuit comprising:

a base that includes power contacts which extend from an upper surface of the base to receive power from a voltage source;

a substrate that is surface mounted to the upper surface of the base, the substrate being electrically coupled to the base; and

a die mounted on the substrate, the die being electrically coupled to the substrate to receive power from the voltage source through the power contacts on the base.

33. (New) The integrated circuit of claim 32, wherein the voltage source is a voltage regulator.

34. (New) The integrated circuit of claim 32, further comprising a heat spreader coupled to the die.